



## Senior Staff Engineer Failure Analysis

### Job description

Perform IC (complex functional) Failure Analysis [FA] on wafer and package level from electrical verification, fault isolation and physical root cause analysis.

- Perform IC (complex functional) Failure Analysis [FA] on wafer and package level from electrical verification, fault isolation and physical root cause analysis.
- Prepare FA reports that can lead to root cause finding and corrective action to cross functional team.
- Participate, lead and present FA results in cross functional meetings, projects, yield improvement, urgent and important meetings.
- FA equipment / tool ownership.
- Interface with designers, test, product, process integration and unit process engineers, problem solving team, CQM team to understand the analysis requirement.
- Identify development opportunity of new EFA techniques and improvise FA skills and techniques to enhance analysis quality, speed and cost
- Responsible for achieving EFA KPIs.
- ATE test knowledge capability
- Setup of application board, product specific test methodology and localization capability.
- CAD navigation, layout and schematic analysis to identify the failure location and hypothesis
- Responsible for Fault Tree Analysis (FTA) in case of no physical defect found

### Profile

- 6+ years working experience particularly related to FA field.

### At a glance

Location: **Kulim (Malaysia)**  
Job ID: **363199**  
Start date: **Sep 01, 2022**  
Entry level: **5+ years**  
Type: **Full time**  
Contract: **Permanent**

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- Degree / Master / Ph D in Electrical and Electronic Engineering
- Knowledge in interpret a product datasheet.
- Have some experience in some of these field of knowledge: Complex Electrical Failure Verification and Localization, i.e. scan logic , Hi-Level Tester, SDL analysis, Sample preparation, i.e. mechanical polishing, precision cleaving, wet/dry chemical, backside preparation, package preparation. Imaging, i.e. optical, SEM and FIB (incl. Voltage Contrast). Repackaging skill i.e. COB, wire bonding, CAD Navigation plus Cross Mapping Schematic, Software Diagnosis on Logic FA Circuit troubleshooting via micro probing (A-pad, FIB pad or AFP) IC package Sample reconditioning, rework experience.

## Benefits

- **Kulim:** Möglichkeit für Coaching, Mentoring & Netzwerken; Trainingsangebot & strukturierte Entwicklungsplanung; Möglichkeit zur internationalen Entsendung; Verschiedene Karrierepfade: Project Management, Technical Ladder, Management & Individual Contributor; Flexible Arbeitszeit: Vertrauensgleitzeit; Ferienbetreuung; Medizinische Absicherung; Sozialberatung & Betriebsarzt; Gesundheits- & Vorsorgeprogramme; Fitness-Studio und Außensportanlagen mit Beachvolleyball, Tennis, Fußball und Laufparcours; Kantine; Versicherungsangebot zu attraktiven Konditionen; Offenheit für flexiblen Übergang in die Altersrente

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